

In the Specification

Page 1, line 1, before "BACKGROUND OF THE INVENTION" please amend the paragraph that was previously inserted there-at as follows:

"CROSS REFERENCE TO RELATED APPLICATION

This application claims the benefit of and is a continuation of Application No. 09/153,630, filed September 15, 1998, now issued as U.S. Patent No. 6,153,829."

Page 8, line 24, please further amend the paragraph beginning there at from the immediate prior version as follows:

"The conductive strips 44 and 46 can be formed by initially masking off all surfaces of the package housing, except the edge 49 of the first bond shelf 18 with a plating resist maskant 50, as shown in Figure 5. The masked housing can then be dipped into a plating bath 52 as shown in Figure 5 6. The plating bath 52 plates a conductive material such as copper onto the edge 49 of the first bond shelf 18. The maskant 50 is then removed and the notches 48 can be drilled into the edges of the first bond shelf 18 to separate the plated material into the first and second conductive strips 44 and 46. All exposed copper surfaces may then be plated with gold."